Thermal Characteristics

Package	I _D I _D (continuous) [†] (pulsed) (MA) (A)		Power Dissipation @T _c = 25°C (W)	θ _{jc} (°C/W)	θ _{ja} (°C/W)	l _{DR} † (mA)	I _{DRM} (A)	
TO-92	300	1.0	1.0	125	170	300	1.0	

Notes:

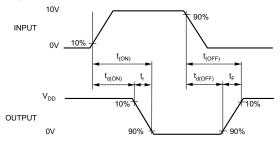
Electrical Characteristics (T_A = 25°C unless otherwise specified)

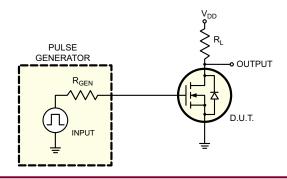
Sym	Parameter	Min	Тур	Max	Units	Conditions	
BV _{DSS}	Drain-to-source breakdown voltage	60	-	-	V	$V_{GS} = 0V, I_D = 1.0 \text{mA}$	
$V_{GS(th)}$	Gate threshold voltage	0.8	-	2.4	V	$V_{GS} = V_{DS}, I_{D} = 1.0 \text{mA}$	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with temperature	-	-3.8	-5.5	mV/°C	$V_{GS} = V_{DS}$, $I_{D} = 1.0$ mA	
l _{GSS}	Gate body leakage current	-	0.1	100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
	Zero gate voltage drain current		-	1.0	μA	$V_{GS} = 0V, V_{DS} = Max Rating$	
l _{DSS}			-	100		$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$, $T_{A} = 125^{\circ}C$	
I _{D(ON)}	On-state drain current	0.6	-	-	Α	$V_{GS} = 10V, V_{DS} = 25V$	
Б	Static drain-to-source on-state resistance	-	4.5	6.0	Ω	V _{GS} = 5.0V, I _D = 75mA	
R _{DS(ON)}		-	3.0	4.0		V _{GS} = 10V, I _D = 500mA	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with temperature	-	0.7	1.0	%/°C	$V_{GS} = 10V, I_{D} = 500mA$	
G _{FS}	Forward transconductance	150	400	-	mmho	$V_{DS} = 25V, I_{D} = 500mA$	
C _{ISS}	Input capacitance		35	50		V _{GS} = 0V,	
C _{oss}	Common source output capacitance	1	13	25	pF	$V_{DS} = 25V$,	
C _{RSS}	Reverse transfer capacitance		4.0	5.0		f = 1.0MHz	
t _{d(ON)}	Turn-on delay time	-	3.0	5.0			
t _r	Rise time Turn-off delay time		5.0	8.0	ns	$V_{DD} = 25V,$ $I_{D} = 600\text{mA},$ $R_{GEN} = 25\Omega$	
t _{d(OFF)}			6.0	9.0			
t _f			5.0	8.0			
V_{SD}	Diode forward voltage drop	-	1.2	1.8	V	$V_{GS} = 0V, I_{SD} = 600 \text{mA}$	
t _{rr}	Reverse recovery time	-	400	-	ns	$V_{GS} = 0V$, $I_{SD} = 600$ mA	

Notes:

- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

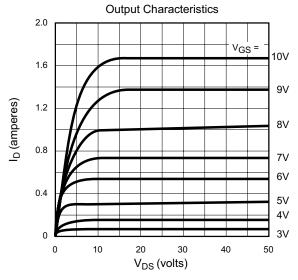
Switching Waveforms and Test Circuit

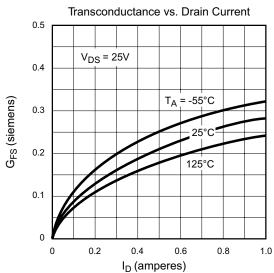


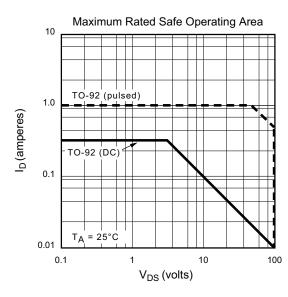


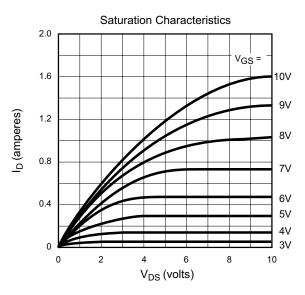
[†] I_D (continuous) is limited by max rated T_i .

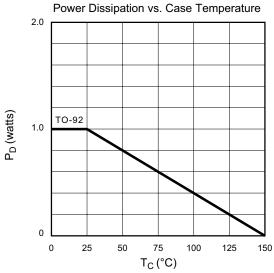
Typical Performance Curves

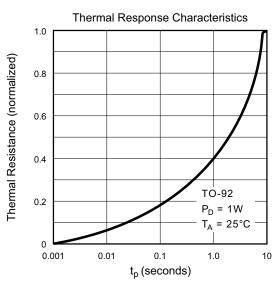




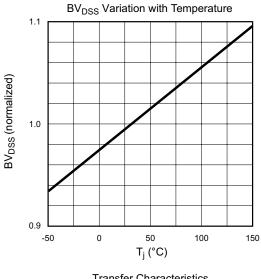


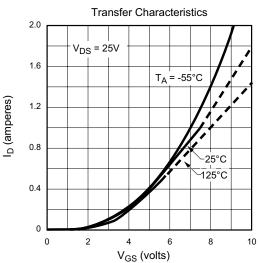


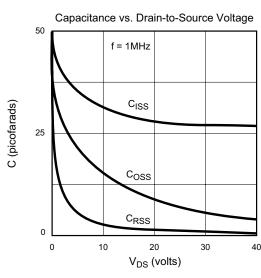


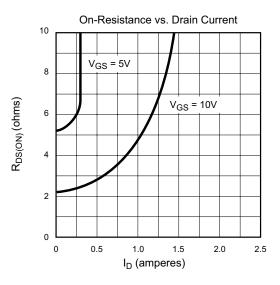


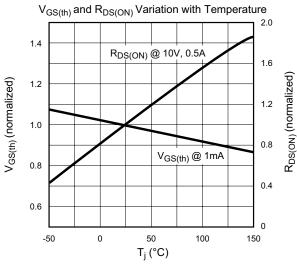
Typical Performance Curves (cont.)

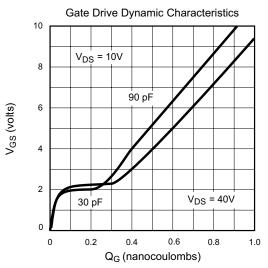




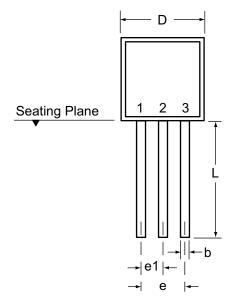


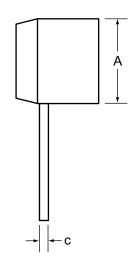






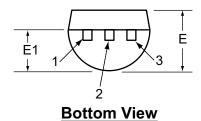
3-Lead TO-92 Package Outline (N3)





Front View

Side View



Symbol		Α	b	С	D	E	E1	е	e1	L
	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
()	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version D080408.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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^{*} This dimension is not specified in the original JEDEC drawing. The value listed is for reference only.

[†] This dimension is a non-JEDEC dimension.